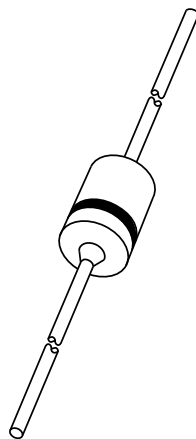


DATA SHEET



1N4148; 1N4446; 1N4448 High-speed diodes

Product specification
Supersedes data of April 1992
File under Discrete Semiconductors, SC01

1996 Apr 15

High-speed diodes

1N4148; 1N4446; 1N4448

FEATURES

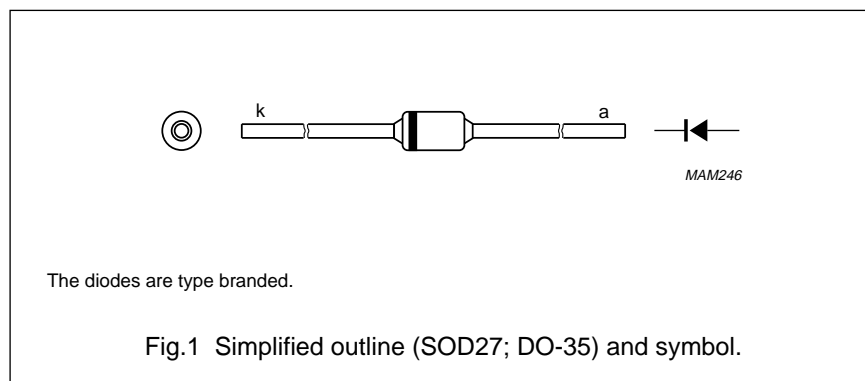
- Hermetically sealed leaded glass SOD27 (DO-35) package
- High switching speed: max. 4 ns
- General application
- Continuous reverse voltage: max. 75 V
- Repetitive peak reverse voltage: max. 75 V
- Repetitive peak forward current: max. 450 mA
- Forward voltage: max. 1 V.

APPLICATIONS

- High-speed switching.

DESCRIPTION

The 1N4148, 1N4446, 1N4448 are high-speed switching diodes fabricated in planar technology, and encapsulated in hermetically sealed leaded glass SOD27 (DO-35) packages.



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{RRM}	repetitive peak reverse voltage		—	75	V
V_R	continuous reverse voltage		—	75	V
I_F	continuous forward current	see Fig.2; note 1	—	200	mA
I_{FRM}	repetitive peak forward current		—	450	mA
I_{FSM}	non-repetitive peak forward current	square wave; $T_j = 25\text{ °C}$ prior to surge; see Fig.4 $t = 1\text{ }\mu\text{s}$ $t = 1\text{ ms}$ $t = 1\text{ s}$	— — —	4 1 0.5	A A A
P_{tot}	total power dissipation	$T_{amb} = 25\text{ °C}$; note 1	—	500	mW
T_{stg}	storage temperature		−65	+200	°C
T_j	junction temperature		—	200	°C

Note

1. Device mounted on an FR4 printed circuit-board; lead length 10 mm.

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ELECTRICAL CHARACTERISTICS $T_j = 25\text{ }^{\circ}\text{C}$; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_F	forward voltage	see Fig.3			
	1N4148	$I_F = 10\text{ mA}$	–	1.0	V
	1N4446	$I_F = 20\text{ mA}$	–	1.0	V
	1N4448	$I_F = 5\text{ mA}$	0.62	0.72	V
		$I_F = 100\text{ mA}$	–	1.0	V
I_R	reverse current	$V_R = 20\text{ V}$; see Fig.5		25	nA
		$V_R = 20\text{ V}$; $T_j = 150\text{ }^{\circ}\text{C}$; see Fig.5	–	50	μA
I_R	reverse current; 1N4448	$V_R = 20\text{ V}$; $T_j = 100\text{ }^{\circ}\text{C}$; see Fig.5	–	3	μA
C_d	diode capacitance	$f = 1\text{ MHz}$; $V_R = 0$; see Fig.6		4	pF
t_{rr}	reverse recovery time	when switched from $I_F = 10\text{ mA}$ to $I_R = 60\text{ mA}$; $R_L = 100\text{ }\Omega$; measured at $I_R = 1\text{ mA}$; see Fig.7		4	ns
V_{fr}	forward recovery voltage	when switched from $I_F = 50\text{ mA}$; $t_r = 20\text{ ns}$; see Fig.8	–	2.5	V

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-tp}$	thermal resistance from junction to tie-point	lead length 10 mm	240	K/W
$R_{th\ j-a}$	thermal resistance from junction to ambient	lead length 10 mm; note 1	350	K/W

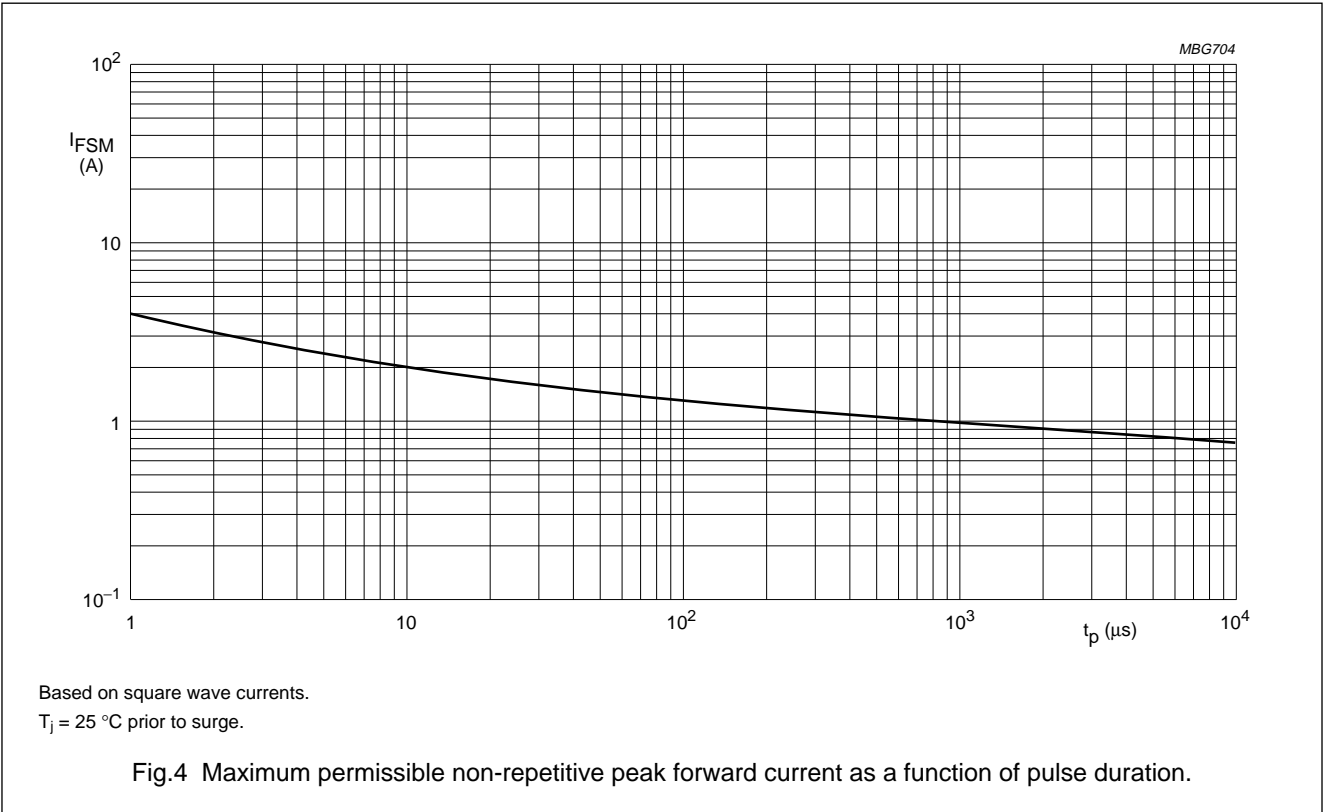
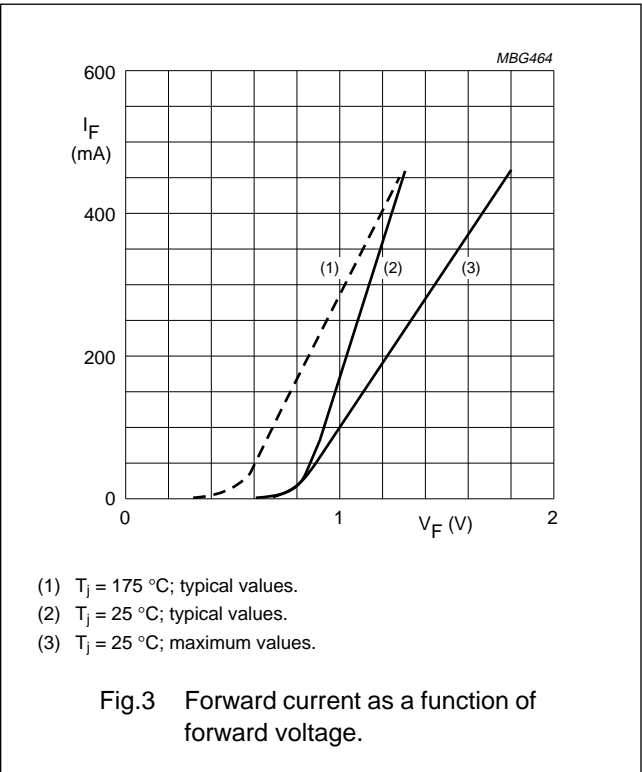
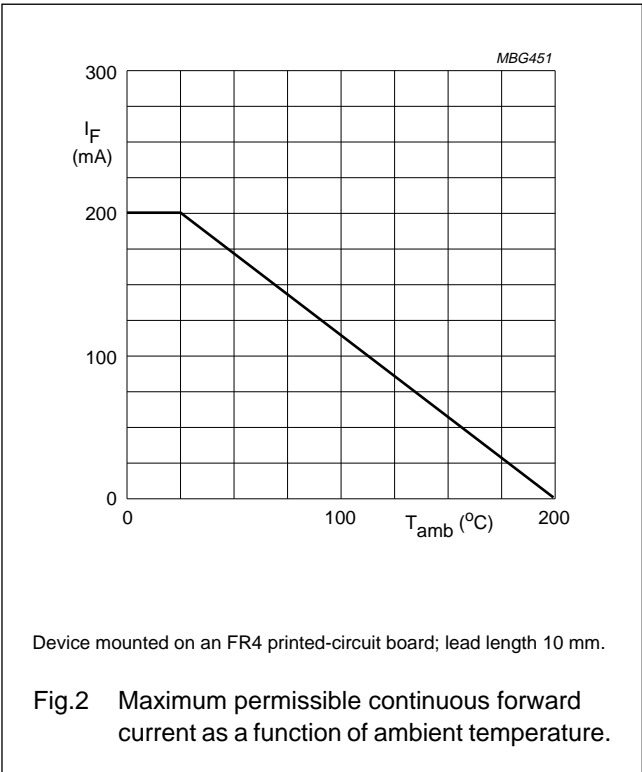
Note

1. Device mounted on a printed circuit-board without metallization pad.

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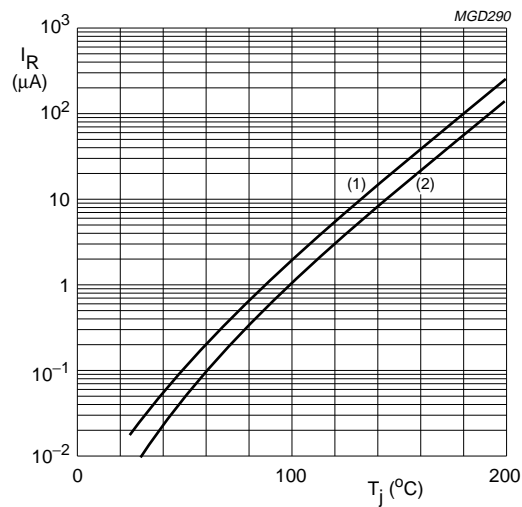
1N4148; 1N4446; 1N4448

GRAPHICAL DATA



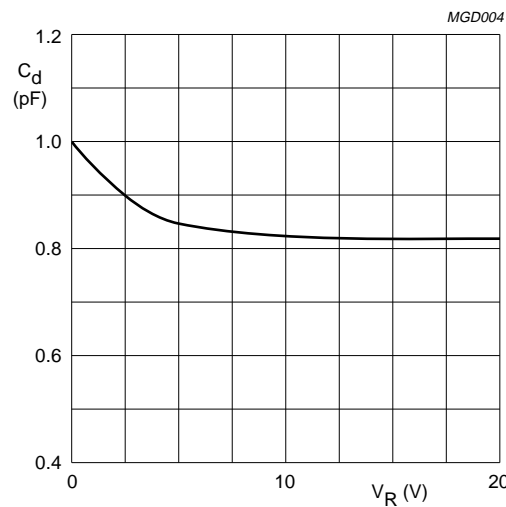
High-speed diodes

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(1) $V_R = 75 V$; typical values.
(2) $V_R = 20 V$; typical values.

Fig.5 Reverse current as a function of junction temperature.

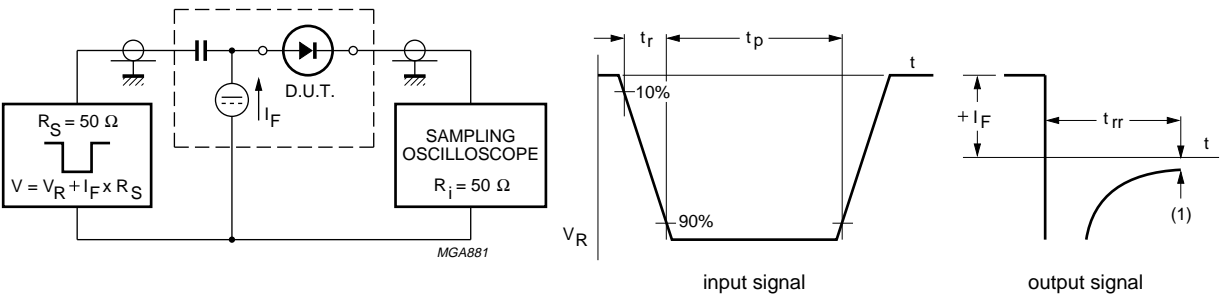


$f = 1 MHz$; $T_j = 25^{\circ}C$.

Fig.6 Diode capacitance as a function of reverse voltage; typical values.

High-speed diodes

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(1) $I_R = 1\text{ mA}$.

Fig.7 Reverse recovery voltage test circuit and waveforms.

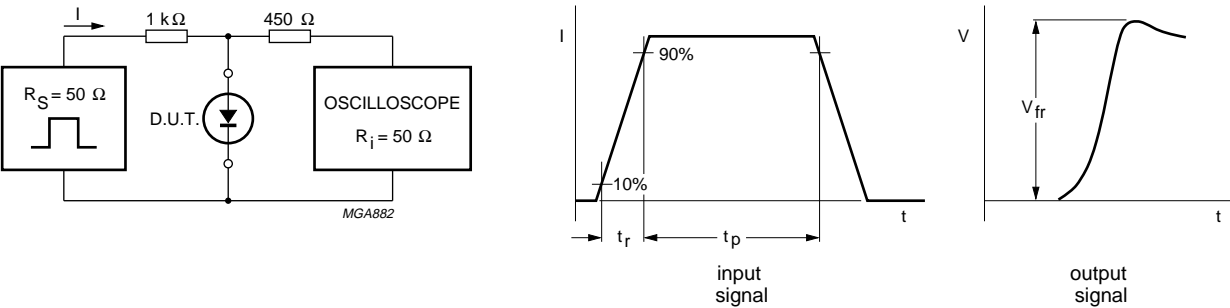
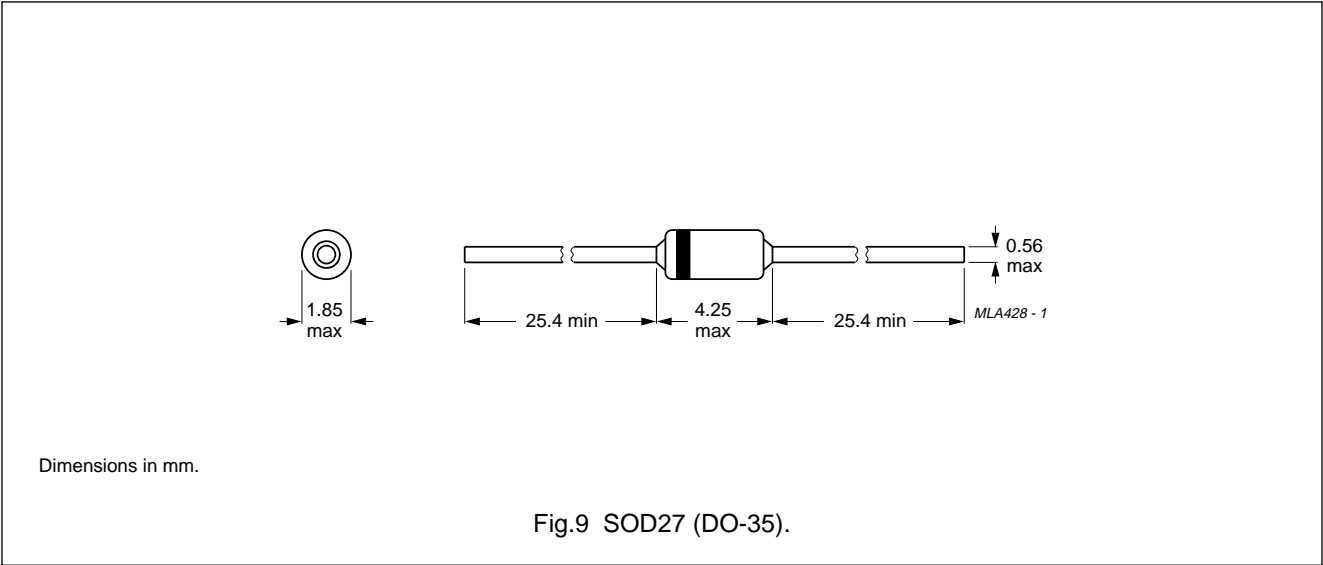


Fig.8 Forward recovery voltage test circuit and waveforms.

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PACKAGE OUTLINE



DEFINITIONS

Data Sheet Status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

LIFE SUPPORT APPLICATIONS

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